

QH8KA1

30V Nch+Nch Power MOSFET

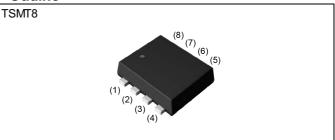
V <sub>DSS</sub>	30V
R <sub>DS(on)</sub> (Max.)	73mΩ
I <sub>D</sub>	±4.5A
PD	2.4W

## Features

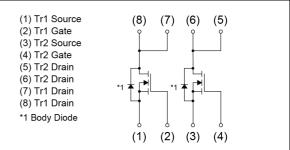
- 1) Low on resistance.
- 2) Small Surface Mount Package (TSMT8).
- 3) Pb-free lead plating ; RoHS compliant.
- 4) Halogen Free.

## Datasheet





#### Inner circuit



### Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TCR
	Marking	KA1

## Application

Switching

Motor Drive

## • Absolute maximum ratings ( $T_a = 25^{\circ}C$ ) <It is the same ratings for the Tr1 and Tr2>

Parameter		Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	30	V	
Continuous drain current		۱ <sub>D</sub> *1	±4.5	А	
Pulsed drain current		I <sub>D, pulse</sub> *2	±12	А	
Gate - Source voltage	V <sub>GSS</sub>	±20	V		
Avalanche energy, single pulse	E <sub>AS</sub> *3	0.65	mJ		
Avalanche current		Ι <sub>ΑS</sub> *3	3	А	
	tetel	P <sub>D</sub> <sup>*1</sup>	2.4		
Power dissipation	total	P <sub>D</sub> <sup>*4</sup>	1.5	W	
	element	P <sub>D</sub> <sup>*4</sup>	1.25		
Junction temperature		T <sub>j</sub>	150	°C	
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C	

### Thermal resistance

Parameter	Symbol	Values			Linit
	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	$R_{thJA}^{*4}$	-	83.3	-	°C/W

## •Electrical characteristics (T<sub>a</sub> = 25°C) <It is the same characteristics for the Tr1 and Tr2>

Deremeter	Symbol Conditions		Values			1 1
Parameter	Symbol	Conditions		Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	30	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	$\Delta V_{(BR)DSS} I_D = 1 mA$ $\Delta T_j \qquad referenced to 25°C$		21	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	$I_{DSS}$ $V_{DS} = 30V, V_{GS} = 0V$		-	1	μA
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V		-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1mA	1.0	-	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	$I_{D} = 1 \text{mA}$ referenced to 25°C		-3	-	mV/°C
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A	-	56	73	
on - state resistance	${\sf R}_{\sf DS(on)}^{*5}$	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.0A	-	86	112	mΩ
Transconductance	${\sf g_{fs}}^{*5}$	V <sub>DS</sub> = 5V, I <sub>D</sub> = 3A	1.7	-	-	S

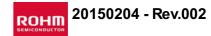
\*1 Pw  $\leq$  1s, Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L  $\simeq$  0.1mH, V\_{DD} = 15V, R\_G = 25 $\Omega$ , STARTING T\_{ch} = 25°C Fig.3-1,3-2

\*4 Mounted on a ceramic board (30×30×0.8mm)

\*5 Pulsed



## •Electrical characteristics (T<sub>a</sub> = 25°C) <It is the same characteristics for the Tr1 and Tr2>

Parameter	Symbol	Conditions		Unit			
	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	125	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15V	-	20	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	15	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 15 V, V_{GS} = 10 V$	-	5.0	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 2.25A	-	7.5	-	120	
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> = 6.67Ω	-	10	-	ns	
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	3.5	-		

## •Gate charge characteristics ( $T_a = 25^{\circ}C$ ) <It is the same characteristics for the Tr1 and Tr2>

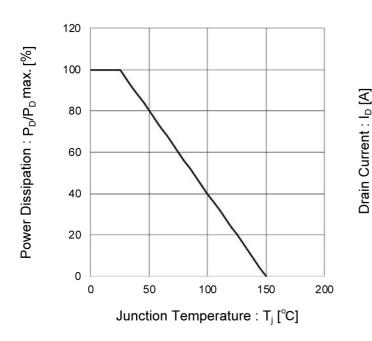
Parameter	Symbol	nbol Conditions -		Values			Unit
	Symbol			Min.	Тур.	Max.	Unit
Tatal wata abawa	O *5		V <sub>GS</sub> = 10V	-	3.0	-	
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 15V I <sub>D</sub> = 4.5A		-	1.5	-	
Gate - Source charge	$Q_{gs}^{*5}$		V <sub>GS</sub> = 4.5V	-	0.6	-	nC
Gate - Drain charge	$Q_{gd}^{*5}$			-	0.5	-	

## •Body diode electrical characteristics (Source-Drain) ( $T_a = 25^{\circ}C$ )

< It is the same characteristics for the Tr1 and Tr2>

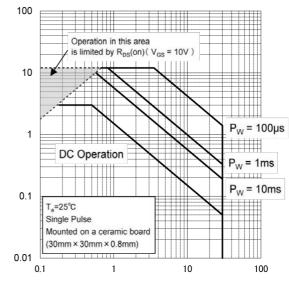
Doromotor	Sumbol	Conditions	Values			Unit
	Parameter Symbol Conditions		Min.	Тур.	Max.	Unit
Body diode continuous forward current	I <sub>S</sub>	T - 25°0	-	-	1.0	^
Body diode pulse current	ا <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	12	A
Forward voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.0A	-	-	1.2	V



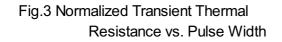


## Fig.1 Power Dissipation Derating Curve

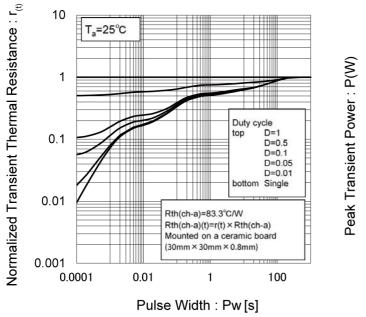
Fig.2 Maximum Safe Operating Area

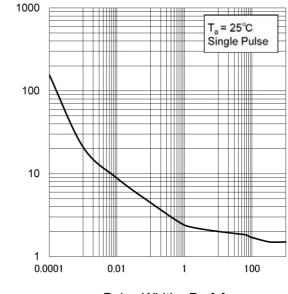


Drain - Source Voltage : V<sub>DS</sub> [V]



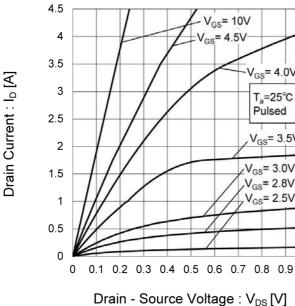
# Fig.4 Single Pulse Maximum Power dissipation





Pulse Width : Pw [s]





### Fig.5 Typical Output Characteristics(I)

V<sub>GS</sub>= 10V

V<sub>GS</sub>= 4.5V

V<sub>GS</sub>= 4.0V

T<sub>a</sub>=25°C Pulsed

V<sub>GS</sub>= 3.5V

V<sub>GS</sub>= 3.0V

V<sub>GS</sub>= 2.8V

V<sub>GS</sub>= 2.5V

1

Fig.6 Typical Output Characteristics(II)

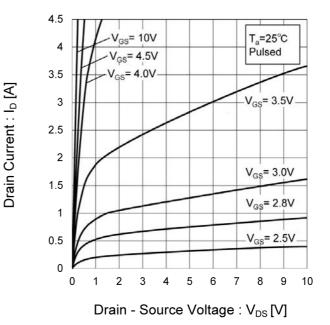
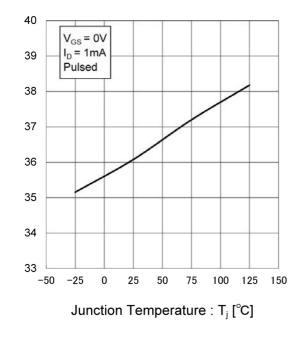
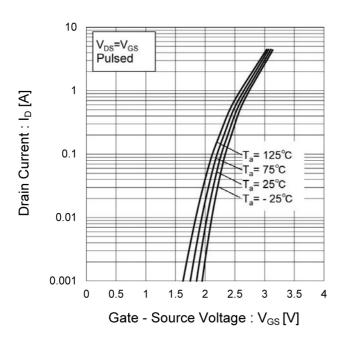


Fig.7 Breakdown Voltage vs. Junction Temperature









## Fig.8 Typical Transfer Characteristics

## Fig.9 Gate Threshold Voltage vs. Junction Temperature

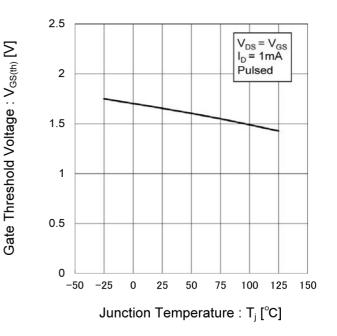
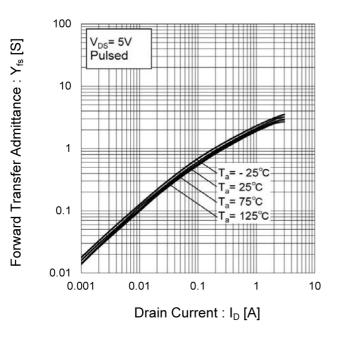


Fig.10 Tranceconductance vs. Drain Current





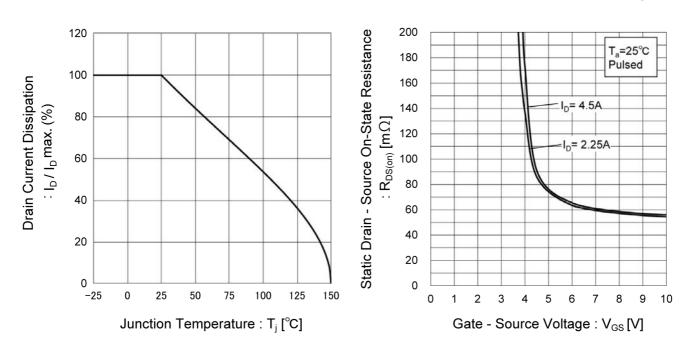


Fig.11 Drain Current Derating Curve

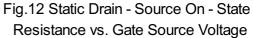
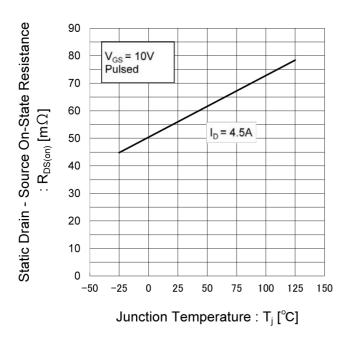


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





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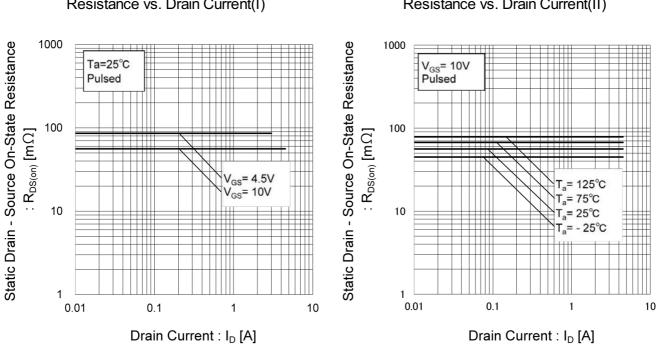
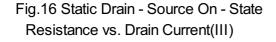
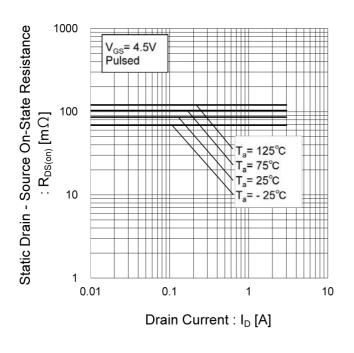
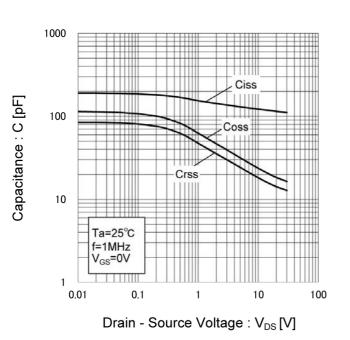


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I) Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)









## Fig.17 Typical Capacitance vs. Drain -Source Voltage

Fig.18 Switching Characteristics

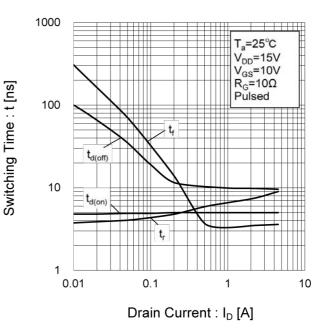


Fig.19 Dynamic Input Characteristics

Gate - Source Voltage : V<sub>GS</sub> [V]

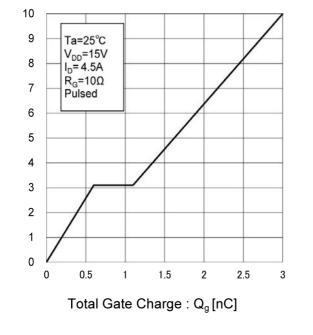
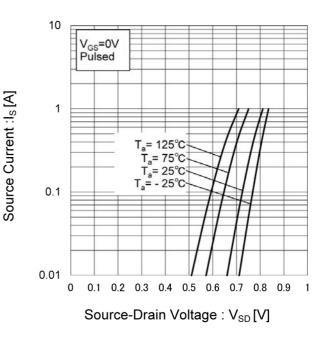


Fig.20 Source Current vs. Source Drain Voltage





## •Measurement circuits <It is the same for the Tr1 and Tr2>



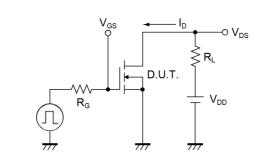


Fig.2-1 Gate Charge Measurement Circuit

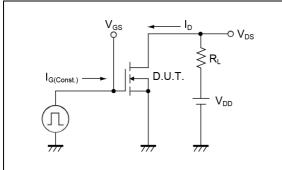


Fig.3-1 Avalanche Measurement Circuit

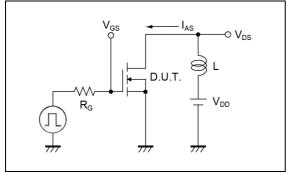


Fig.1-2 Switching Waveforms

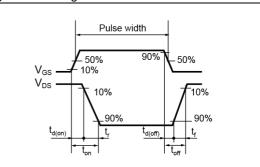
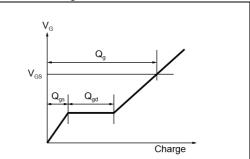
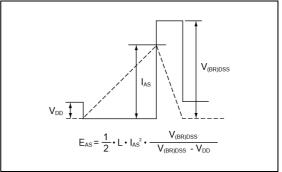


Fig.2-2 Gate Charge Waveform



#### Fig.3-2 Avalanche Waveform

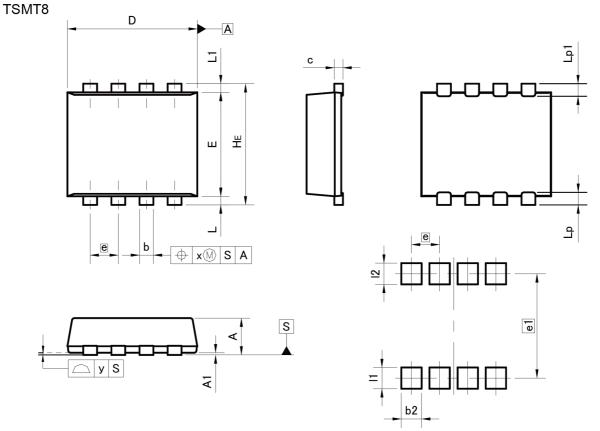


### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



### Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

D.114	MILIM	MILIMETERS		HES	
DIM	MIN	MAX	MIN	MAX	
A	0.75	0.85	0.030	0.033	
A1	0.00	0.05	0.000	0.002	
b	0.27	0.37	0.011	0.015	
с	0.12	0.22	0.005	0.009	
D	2.90	3.10	0.114	0.122	
E	2.30	2.50	0.091	0.098	
е	0.	65	0.0	26	
HE	2.70	2.90	0.106	0.114	
L	0.10	0.30	0.004	0.012	
L1	0.10	0.30	0.004	0.012	
Lp	0.19	0.39	0.007	0.015	
Lp1	0.19	0.39	0.007	0.015	
x	-	0.10	-	0.004	
у	-	0.10	-	0.004	
	MIL IM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
b2	-	0.47	-	0.019	
e1	2.	41	0.0	95	
11		0.49	<u></u>	0.019	
12		0.49		0.019	

Dimension in mm/inches



## Notice

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	CLASSⅣ	CLASSII	CLASSII	CLASSI

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  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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